



# UNITED STATES PATENT AND TRADEMARK OFFICE

UNITED STATES DEPARTMENT OF COMMERCE  
United States Patent and Trademark Office  
Address: COMMISSIONER FOR PATENTS  
P.O. Box 1450  
Alexandria, Virginia 22313-1450  
www.uspto.gov

APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/709,179	04/19/2004	Chih-Huang Chang	10544-US-PA	3178

  

31561	7590	12/13/2007
JIANQ CHYUN INTELLECTUAL PROPERTY OFFICE		
7 FLOOR-1, NO. 100		
ROOSEVELT ROAD, SECTION 2		
TAIPEI, 100		
TAIWAN		

  

EXAMINER	
HA, NATHAN W	

  

ART UNIT	PAPER NUMBER
2814	

  

NOTIFICATION DATE	DELIVERY MODE
12/13/2007	ELECTRONIC

**Please find below and/or attached an Office communication concerning this application or proceeding.**

The time period for reply, if any, is set in the attached communication.

Notice of the Office communication was sent electronically on above-indicated "Notification Date" to the following e-mail address(es):

USA@JCIPGROUP.COM.TW

<b>Office Action Summary</b>	<b>Application No.</b>	<b>Applicant(s)</b>	
	10/709,179	CHANG ET AL.	
	<b>Examiner</b>	<b>Art Unit</b>	
	Nathan W. Ha	2814	

**-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --**

**Period for Reply**

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) OR THIRTY (30) DAYS, WHICHEVER IS LONGER, FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If NO period for reply is specified above, the maximum statutory period **will** apply and **will** expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply **will**, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

**Status**

- 1) ☒ Responsive to communication(s) filed on 27 November 2007.
- 2a) ☐ This action is **FINAL**.                      2b) ☒ This action is non-final.
- 3) ☐ Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

**Disposition of Claims**

- 4) ☒ Claim(s) 15-20 is/are pending in the application.
- 4a) Of the above claim(s) \_\_\_\_\_ is/are withdrawn from consideration.
- 5) ☐ Claim(s) \_\_\_\_\_ is/are allowed.
- 6) ☒ Claim(s) 15-20 is/are rejected.
- 7) ☐ Claim(s) \_\_\_\_\_ is/are objected to.
- 8) ☐ Claim(s) \_\_\_\_\_ are subject to restriction and/or election requirement.

**Application Papers**

- 9) ☐ The specification is objected to by the Examiner.
- 10) ☐ The drawing(s) filed on \_\_\_\_\_ is/are: a) ☐ accepted or b) ☐ objected to by the Examiner.  
Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).  
Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).
- 11) ☐ The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.

**Priority under 35 U.S.C. § 119**

- 12) ☐ Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).
- a) ☐ All    b) ☐ Some \*    c) ☐ None of:
1. ☐ Certified copies of the priority documents have been received.
  2. ☐ Certified copies of the priority documents have been received in Application No. \_\_\_\_\_.
  3. ☐ Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).

\* See the attached detailed Office action for a list of the certified copies not received.

**Attachment(s)**

- |  |   |
|--|---|
| 1) <input checked="" type="checkbox"/> Notice of References Cited (PTO-892)          | 4) <input type="checkbox"/> Interview Summary (PTO-413)           |
| 2) <input type="checkbox"/> Notice of Draftsperson's Patent Drawing Review (PTO-948) | Paper No(s)/Mail Date. _____                                      |
| 3) <input type="checkbox"/> Information Disclosure Statement(s) (PTO/SB/08)          | 5) <input type="checkbox"/> Notice of Informal Patent Application |
| Paper No(s)/Mail Date _____  | 6) <input type="checkbox"/> Other: _____                          |

## DETAILED ACTION

### ***Claim Rejections - 35 USC § 102***

1. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless –

(e) the invention was described in (1) an application for patent, published under section 122(b), by another filed in the United States before the invention by the applicant for patent or (2) a patent granted on an application for patent by another filed in the United States before the invention by the applicant for patent, except that an international application filed under the treaty defined in section 351(a) shall have the effects for purposes of this subsection of an application filed in the United States only if the international application designated the United States and was published under Article 21(2) of such treaty in the English language.

2. Claims 15 and 18 are rejected under 35 U.S.C. 102(e) as being anticipated by Yang et al. (US 6768190 B2, newly cited, hereinafter, Yang.)

In regard to claim 15, in fig. 2, Yang discloses a method of fabricating bumps on a chip, the process comprising:

providing a chip 120 with an active surface (top surface) having a plurality of bonding pads (or line pad) 1261 thereon and a backside (bottom side.)

forming at least a bump pad 124 on the backside of the chip; and

forming a bump 140 directly on the bump pad.

In regard to claim 18, Yang further shows forming the protective element 227 on the active surface of the chip. Fig. 4.

***Claim Rejections - 35 USC § 103***

3. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negated by the manner in which the invention was made.

4. Claims 16-17 and 19 are rejected under 35 U.S.C. 103(a) as being unpatentable over Yang as applied to claims 15-16 above, and further in view of Akram (US 6,861,763, previously cited.)

In regard to claims 17 and 19, Yang discloses all of the claimed limitations as mentioned above except the mask has at least an opening so that the backside of the chip is exposed.

Akram, in fig. 6A, discloses an analogous package includes chip 12 pad 14, mask 30C wherein mask layer, or passivation layer, has an opening so the chip is exposed and forming a metallic layer 14 over the mask and the exposed portion of the chip. This opening further provides access to the to the chip for electrical connections. The mask or passivation layer then further removed to form a solder ball therein.

Therefore, it would have been obvious to one of ordinary skill in the art at the time of the invention was made to recognize opening portions on the chip in order to provide electrical connections.

In regard to claim 16, Akram shows that the conductive can be made me pattern metal layer, for example, layer 14. This method is commonly used in semiconductor packaging. See Akram's fig. 6A, for example.

5. Claim 20 is rejected under 35 U.S.C. 103(a) as being unpatentable over Yang as applied to claims 15 and 18 above, and further in view of Koh (US 2004/0135266, previously cited.)

In regard to claim 20, Yang discloses all of the claimed limitations as mentioned above, except using a wire-bonding machine in the process of making the electrical connection elements, bond pad, for example. It should be noted that wire bonding is widely used in the semiconductor package to form wire connections, bonding pad, and solder balls since it is widely available and provides easy access to such small area on the chip.

Therefore, it would have been obvious to one of ordinary skill in the art at the time of the invention was made to recognize the method as taught by Koh in order to facilitate the method of forming electrical connection elements.

### ***Response to Arguments***

6. Applicant's arguments with respect to claim 14 have been considered but are moot in view of the new ground(s) of rejection.

### ***Conclusion***

7. The prior art made of record and not relied upon is considered pertinent to applicant's disclosure. For example, US 6777799 B2 also describes a chip with connection pad on an active surface and bump pads on the opposite surface and bumps directly formed on the bump pads.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Nathan W. Ha whose telephone number is (571) 272-1707. The examiner can normally be reached on M-TH 8:00-7:00(EST).

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Wael Fahmy can be reached on (571) 272-1705. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see <http://pair-direct.uspto.gov>. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

/Nathan W. Ha/  
Primary Examiner, Art Unit 2814